Materials Declaration Form

IPC	**1752**	**Version**	**2**
Form Type *	**Distribute**		
Sectionals *	**Material Info** **Manufacturing Info**	**Subsectionals ***	**A-D**
			***: Required Field**

Supplier Information			
Company Name *	**STMicroelectronics**	**Response Date ***	**2016-08-01**
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	**Rossana Bonaccorso**	**Representative Title**	**ADG MD Champion**
Representative Phone *	Refer to Supplier Comment section	**Representative Email ***	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	**true**	**Legal Declaration ***	**Standard**

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier’s liability and the Company’s remedies for issues that arise regarding information the Supplier provides in this form.

Signature Not
Verified

Digitally signed by
rossana bonaccorso
Date: 2016.08.01
12:00:50 +02:00

Product

Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STD95P3LLH6AG	XMDP*6B37A62	A	SHENZHEN B/E	2016-08-01
	Amount	**UoM**	**Unit type**	**ST ECOPACK Grade**
	330.00	mg	Each	ECOPACK1

Manufacturing information

J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	6.5-6.1-2.3	3	GULL WING	
Comment	TO 252 DPAK			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	**Response**
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	**true**
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false

Exemption Id.	**Description**
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-20th June 2016	
Query	**Response**
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH	**true**

CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						**Mfr Item Name**	**XMDP*6B37A62**					
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die	Other inorganic materials	5.048	mg	supplier	die	Silicon (Si)	7440-21-3		4.882	mg	967116	14794
				supplier	metallization	Aluminium (Al)	7429-90-5		0.059	mg	11688	179
				supplier	Passivation	Silicon Nitride	12033-89-5		0.021	mg	4160	64
				supplier	Passivation	Silicon Oxide	7631-86-9		0.028	mg	5547	84
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.005	mg	990	15
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.041	mg	8122	124
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.012	mg	2377	36
Leadframe	Copper & its alloys	166.150	mg	supplier	alloy	Copper (Cu)	7440-50-8		164.152	mg	987975	497430
				supplier	alloy	CopperPosphorous (CuP)	12517-41-8		0.330	mg	1986	1000
				supplier	alloy	Cobalt (Co)	7440-48-4		0.462	mg	2781	1400
				supplier	metallization	Nickel (Ni)	7440-02-0		1.199	mg	7216	3633
				supplier	metallization	Phosphorus (P)	12185-10-3		0.007	mg	42	21
Die attach	Other Organic Materials	6.418	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	6.130	mg	955126	18576
				supplier	solder	Silver (Ag)	7440-22-4		0.160	mg	24930	485
				supplier	solder	Tin (Sn)	7440-31-5		0.128	mg	19944	388
Bonding wires	Other inorganic materials	0.831	mg	supplier	wire	Aluminium (Al)	7429-90-5		0.827	mg	994947	2506
				supplier	wire	Magnesium (Mg)	7439-95-4		0.004	mg	5053	13
Encapsulation	Other Organic Materials	150.508	mg	supplier	mold compound	Silica, vitreous	60676-86-0		121.309	mg	805997	367603
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		10.536	mg	70003	31927
				supplier	mold compound	Phenol resin	9003-35-4		6.020	mg	39998	18242
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		9.030	mg	59997	27364
				supplier	mold compound	Antimony Trioxide	1309-64-4		1.806	mg	11999	5473
				supplier	mold compound	Brominated Epoxy Resin	40039-93-8		1.054	mg	7003	3194
				supplier	mold compound	Carbon black	1333-86-4		0.753	mg	5003	2282
Connections coating	Solder	1.045	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.045	mg	1000000	3167